Supporting Information

A detailed investigation of the solvent bonding process for microfluidic chip fabrication in micrometer scale†

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Fig. S1 Influence of post-activation treatments on plastic energy (dashed) and stiffness data (solid lines). Samples activated for a different time have either been evacuated at 0.8 mbar or isothermally tempered at 80°C for 1 h each. Percentage values are given relative to those measured on untreated, injected moulded chips (100%).
Fig. S2 A matrix of 32 x 32 measurement points provides higher resolution, but does suffer from the mutual influence of subsequent measurements. The matrix is acquired in vertical sections from left to right of the 20 µm image.